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PRODUCT CHANGE NOTIFICATION

PCN: PCN173802

Date: September 19, 2017

Subject: Qualification of G700LS Mold Compound and Roughened NiPdAu Leadframe for Select 8-Lead SOIC Commercial and Industrial Products Assembled at Amkor Philippines 1

Change Type: Major

Description of Change:

Cypress announces the qualification of G700LS mold compound and roughened NiPdAu leadframe for select 8-Lead SOIC Commercial and Industrial products assembled at Amkor Philippines 1 (P1).

This mold compound is consistent with Cypress' drive to Green and Pb-free RoHS compliant packages. In addition, this Green and Pb-free G700LS mold compound is compatible with industry standard reflow temperatures for applicable package volume, thickness and lead finish. This new roughened NiPdAu leadframe is compatible with industry standards.

The select 8-Lead SOIC packages are assembled at Amkor Philippines 1 (P1) using the following Bill of Materials:

Material	New Amkor P1 Bill of Materials	Current Amkor P1 Bill of Materials
Mold Compound	Sumitomo G700LS	Sumitomo 6600H
Leadfinish	NiPdAu (Roughened surface)	Pure Sn (Smooth surface)
Die Attach Material	Ablestik 8290	Ablestik 8290
Bond Wire	1.0 mil Au	1.0 mil Au

Benefit of Change:

The qualification of the G700LS mold compound and roughened NiPdAu leadframe allows for an improvement in product reliability and product cycle time.

Part Numbers Affected: 4

See the attached 'Affected Parts List' file for a list of all part numbers affected by this change. Note that any new parts that are introduced after the publication of this PCN will include all changes outlined in this PCN.

Qualification Status:

This change has been qualified through a series of tests documented in the Qualification Test Plan QTP173603. This qualification report can be found as an attachment to this PCN or by visiting www.cypress.com and typing the QTP number in the keyword search window.

Sample Status:

Qualification samples may not be built ahead of time for all part numbers affected by this change. Please review the attached 'Affected Parts List' file for a list of affected part numbers with their associated Amkor Philippines 1 (P1) sample ordering part numbers. Samples are available now unless there is an indication that the sample ordering part numbers are subject to lead times. If you require qualification samples, please contact your local Cypress sales representative as soon as possible, preferably within 30 days of the date of this PCN, to place any sample orders.

Approximate Implementation Date

Effective 90 days from the date of this notification or upon customer approval, whichever comes first, all shipments of the affected part numbers in the attached file will be assembled at Amkor Philippines 1 (P1) or other approved assembly sites.

Anticipated Impact:

Products assembled with the G700LS mold compound and roughened NiPdAu leadframe are completely compatible with existing products from a functional, parametric, and quality performance perspective.

Cypress also recommends that customers take this opportunity to review these changes against current application notes, system design considerations and customer environment conditions to assess impact (if any) to their application.

Method of Identification:

Cypress maintains traceability of product to wafer level, including wafer fabrication location, through the lot number marked on the package.

Response Required:

No response is required.

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at pcn_adm@cypress.com.

Sincerely,

Cypress PCN Administration

Item Marketing Part Number

- 1 CY2305CSXC-1H
- 2 CY2305CSXC-1HT
- 3 CY2305CSXI-1H
- 4 CY2305CSXI-1HT